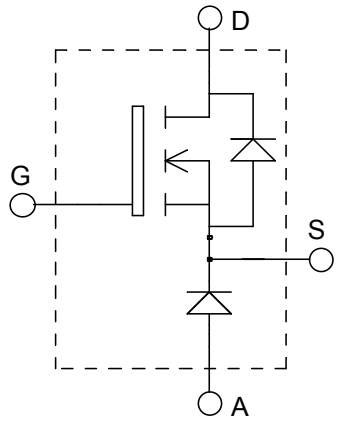
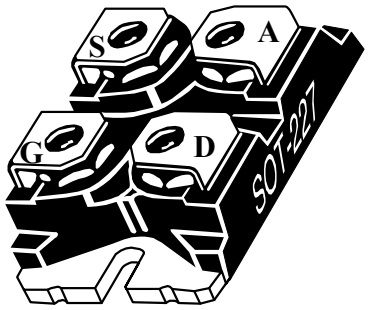
APT58M50JU3

ISOTOP® Buck chopper MOSFET Power Module

V_{DSS} = 500V
R_{DSon} = 65mΩ Max @ Tj = 25°C
I_D = 58A @ Tc = 25°C





ISOTOP®

Application

- AC and DC motor control
- Switched Mode Power Supplies

Features

- Power MOS 8™ MOSFETs
  - Low R_{DSon}
  - Low input and Miller capacitance
  - Low gate charge
  - Avalanche energy rated
  - Very rugged
- ISOTOP® Package (SOT-227)
- Very low stray inductance
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCEsat
- RoHS Compliant

Absolute maximum ratings

Symbol	*Parameter*		*Max ratings*	*Unit*
V_{DSS}	Drain - Source Breakdown Voltage		500	V
I_D	Continuous Drain Current	T_c = 25°C	58	A
		T_c = 80°C	43	
I_{DM}	Pulsed Drain current		270	
V_{GS}	Gate - Source Voltage		±30	V
R_{DSon}	Drain - Source ON Resistance		65	mΩ
P_D	Maximum Power Dissipation	T_c = 25°C	543	W
I_{AR}	Avalanche current (repetitive and non repetitive)		42	A

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ T_j = 25°C unless otherwise specified

Electrical Characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 500V V_{GS} = 0V	T_j = 25°C			250	µA
			T_j = 125°C			1000	
$R_{DS(on)}$	Drain – Source on Resistance	V_{GS} = 10V, I_D = 42A				65	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS} = V_{DS}, I_D = 2.5mA		3	4	5	V
I_{GSS}	Gate – Source Leakage Current	V_{GS} = ±30 V				±100	nA

Dynamic Characteristics

Symbol	*Characteristic*	*Test Conditions*	*Min*	*Typ*	*Max*	*Unit*
C_{iss}	Input Capacitance	V_{GS} = 0V V_{DS} = 25V f = 1MHz		10800		pF
C_{oss}	Output Capacitance			1164		
C_{rss}	Reverse Transfer Capacitance			148		
Q_g	Total gate Charge	V_{GS} = 10V V_{Bus} = 250V I_D = 42A		340		nC
Q_{gs}	Gate – Source Charge			75		
Q_{gd}	Gate – Drain Charge			155		
$T_{d(on)}$	Turn-on Delay Time	**Resistive switching @ 25°C** V_{GS} = 15V V_{Bus} = 333V I_D = 42A R_G = 2.2Ω		60		ns
T_r	Rise Time			70		
$T_{d(off)}$	Turn-off Delay Time			155		
T_f	Fall Time			50		

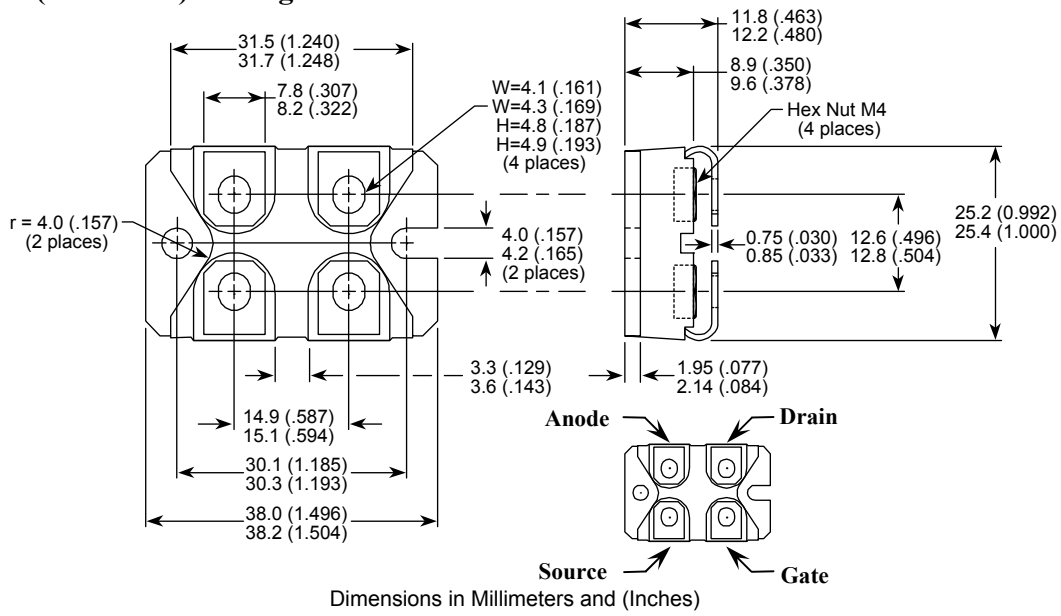
Chopper diode ratings and characteristics

Symbol	*Characteristic*	*Test Conditions*		*Min*	*Typ*	*Max*	*Unit*
V_{RRM}	Maximum Peak Repetitive Reverse Voltage			600			V
I_{RM}	Maximum Reverse Leakage Current	V_R=600V	T_j = 25°C			25	µA
			T_j = 125°C			500	
I_F	DC Forward Current		Tc = 90°C		30		A
V_F	Diode Forward Voltage	I_F = 30A			1.8	2.2	V
		I_F = 60A			2.2		
		I_F = 30A	T_j = 125°C		1.5		
t_{rr}	Reverse Recovery Time	I_F = 30A V_R = 400V di/dt =200A/µs	T_j = 25°C		25		ns
			T_j = 125°C		160		
Q_{rr}	Reverse Recovery Charge		T_j = 25°C		35		nC
			T_j = 125°C		480		

Thermal and package characteristics

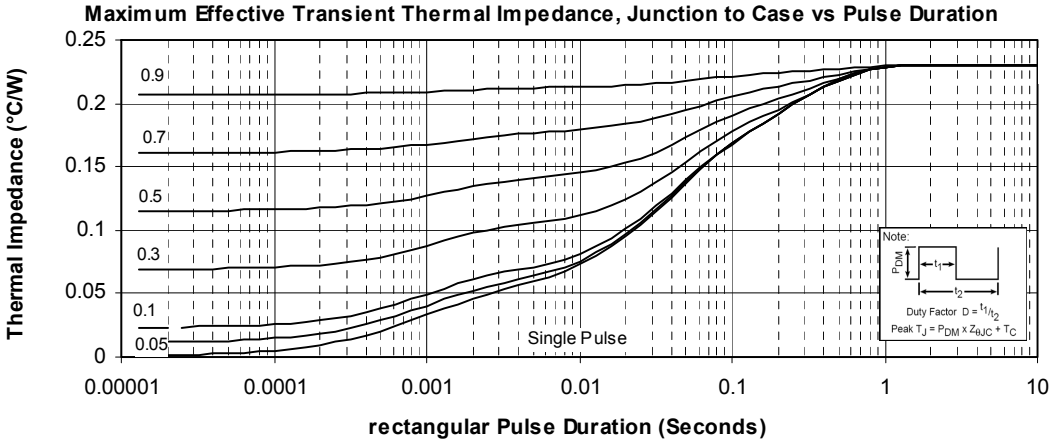
Symbol	*Characteristic*		*Min*	*Typ*	*Max*	*Unit*
R_{thJC}	Junction to Case Thermal Resistance	Mosfet			0.23	°C/W
		Diode			1.05	
R_{thJA}	Junction to Ambient (IGBT & Diode)				20	
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz		2500			V
T_J,T_{STG}	Storage Temperature Range		-40		150	°C
T_L	Max Lead Temp for Soldering:0.063" from case for 10 sec				300	
Torque	Mounting torque (Mounting = 8-32 or 4mm Machine and terminals = 4mm Machine)				1.5	N.m
Wt	Package Weight			29.2		g

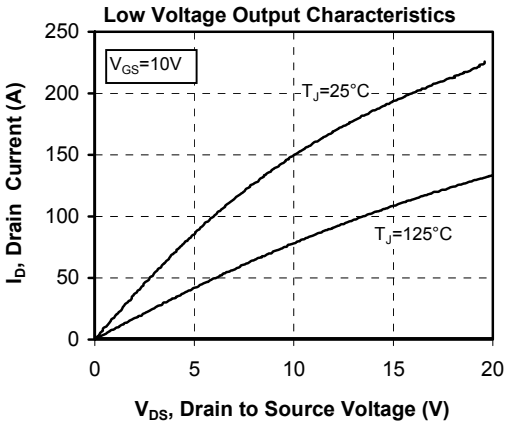
SOT-227 (ISOTOP®) Package Outline

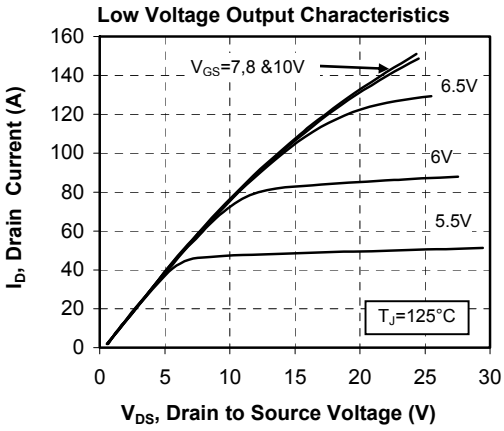


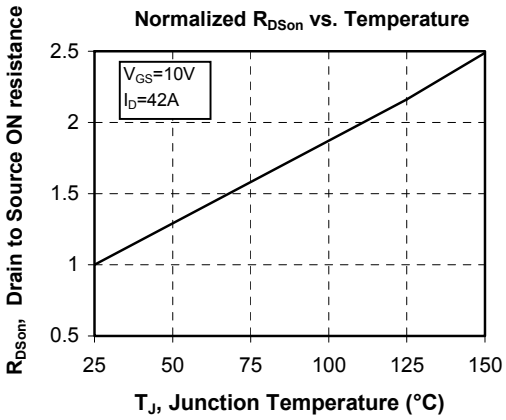
Dimensions in Millimeters and (Inches)

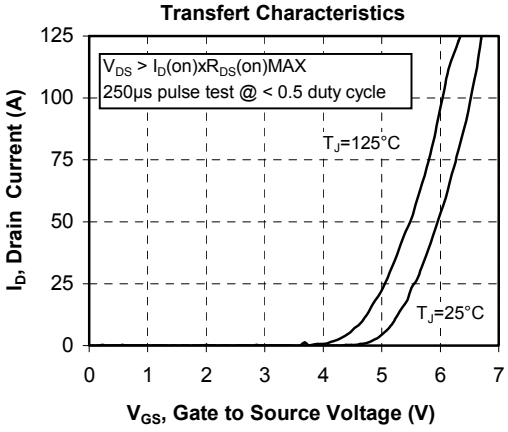
Typical Mosfet Performance Curve

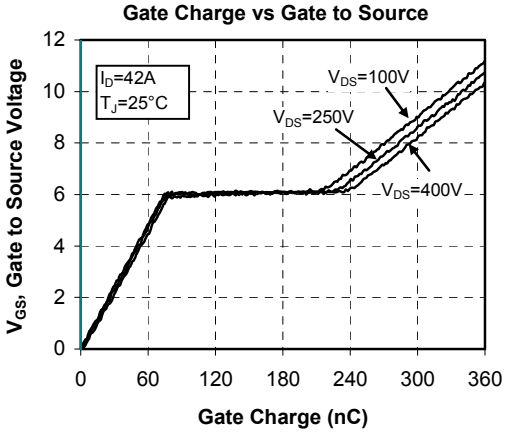


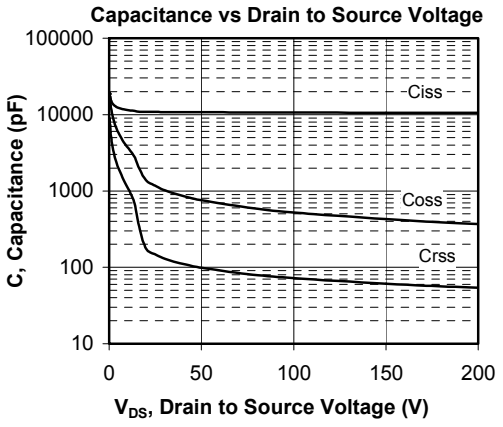




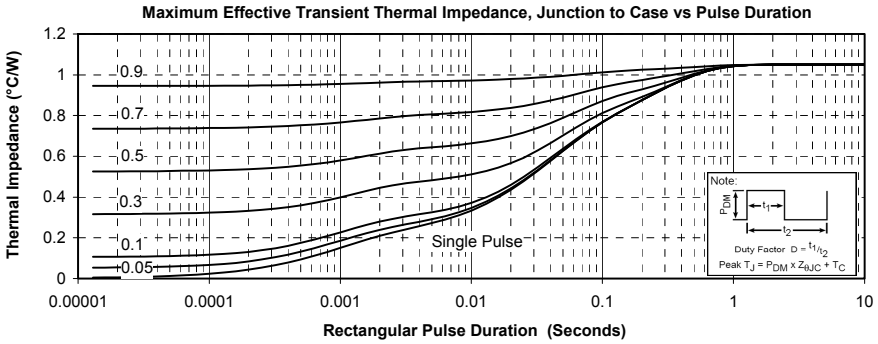


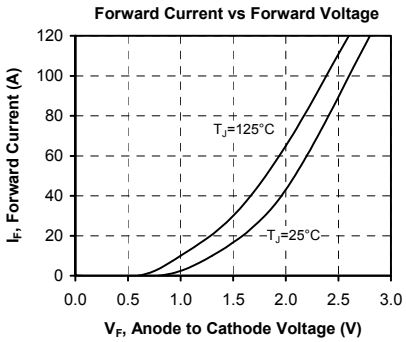


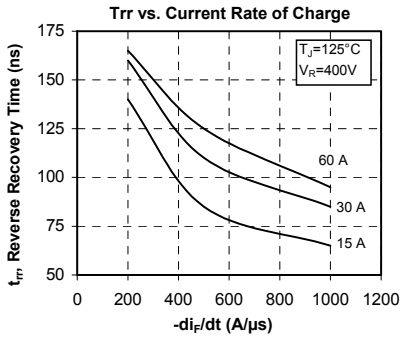


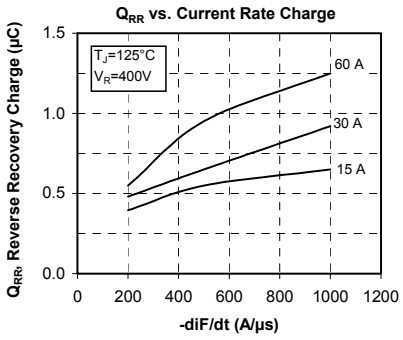


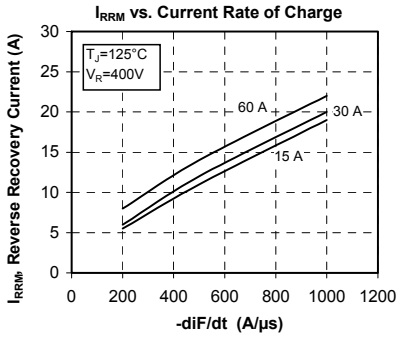
Typical Diode Performance Curve

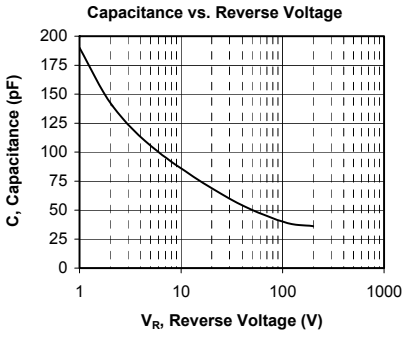


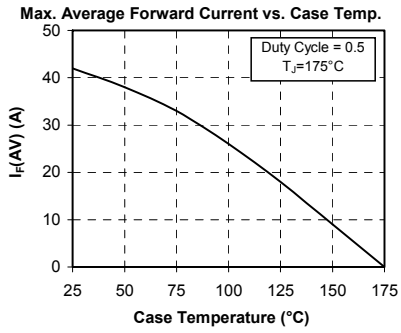












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